CD54HC354, CD74HC354, CD74HCT354

8-Line to 1-Line Data Selector/Multiplexer/Register With 3-State Outputs

SCHS277D - November 1997 - Revised May 2003

Features

- **HC/HCT354**
  - **Transparent Data and Select Latches**
- **Buffered Inputs**
- **Three-State Complementary Outputs**
- **Bus Line Driving Capability**
- **Typical Propagation Delay: V_{CC} = 5V, C_L = 15pF, T_A = 25^oC**
  - **Data to Output = 18ns**
- **Fanout (Over Temperature Range)**
  - **Standard Outputs . . . . . 10 LSTTL Loads**
  - **Bus Driver Outputs . . . . . 15 LSTTL Loads**
- **Wide Operating Temperature Range . . . -55^oC to 125^oC**
- **Balanced Propagation Delay and Transition Times**
- **Significant Power Reduction Compared to LSTTL Logic ICs**
- **HC Types**
  - **2V to 6V Operation**
  - **High Noise Immunity: N_{IL} = 30%, N_{IH} = 30% of V_{CC} at V_{CC} = 5V**
- **HCT Types**
  - **4.5V to 5.5V Operation**
  - **Direct LSTTL Input Logic Compatibility, V_{IL}= 0.8V (Max), V_{IH} = 2V (Min)**
  - **CMOS Input Compatibility, $I_I \leq 1\mu A$ at V_{OL}, V_{OH}**

Description

The CD54HC354, CD74HC354, and CD74HCT354 are data selectors/multiplexers that select one of eight sources. In both types, the data select bits S0, S1 and S2 are stored in transparent latches that are enabled by a low latch enable input, $\overline{LE}$.

In the HC/HCT354 the data enable input, $\overline{E}$, controls transparent latches that pass data to the outputs when $\overline{E}$ is high and latches in new data when $\overline{E}$ is low.

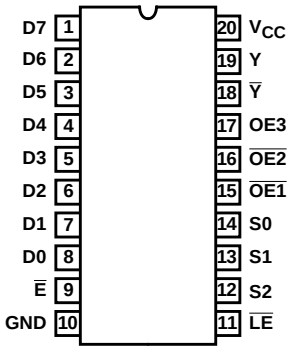
In both types the three-state outputs are controlled by three output-enable inputs $\overline{OE1}$, $\overline{OE2}$, and OE3.

Ordering Information

PART NUMBER	TEMP. RANGE (^oC)	PACKAGE
CD54HC354F3A	-55 TO 125	20 Ld CERDIP
CD74HC354E	-55 to 125	20 Ld PDIP
CD74HCT354E	-55 to 125	20 Ld PDIP

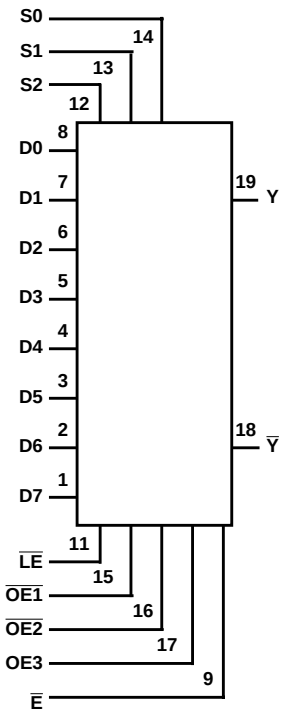
Pinout

CD54HC354
(CERDIP)
CD74HC354, CD74HCT354
(PDIP)
TOP VIEW



CAUTION: These devices are sensitive to electrostatic discharge. Users should follow proper IC Handling Procedures.

Functional Diagram



TRUTH TABLE

INPUTS							OUTPUTS	
SELECT (NOTE 1)			ENABLE DATA	OUTPUT ENABLES				
S2	S1	S0	$\overline{E}$	$\overline{OE1}$	$\overline{OE2}$	OE3	$\overline{Y}$	Y
X	X	X	X	H	X	X	Z	Z
X	X	X	X	X	H	X	Z	Z
X	X	X	X	X	X	L	Z	Z
L	L	L	L	L	L	H	$\overline{D0}$	D0
L	L	L	H	L	L	H	$\overline{D0}_n$	$D0_n$
L	L	H	L	L	L	H	$\overline{D1}$	D1
L	L	H	H	L	L	H	$\overline{D1}_n$	$D1_n$
L	H	L	L	L	L	H	$\overline{D2}$	D2
L	H	L	H	L	L	H	$\overline{D2}_n$	$D2_n$
L	H	H	L	L	L	H	$\overline{D3}$	D3
L	H	H	H	L	L	H	$\overline{D3}_n$	$D3_n$
H	L	L	L	L	L	H	$\overline{D4}$	D4
H	L	L	H	L	L	H	$\overline{D4}_n$	$D4_n$
H	L	H	L	L	L	H	$\overline{D5}$	D5
H	L	H	H	L	L	H	$\overline{D5}_n$	$D5_n$
H	H	L	L	L	L	H	$\overline{D6}$	D6
H	H	L	H	L	L	H	$\overline{D6}_n$	$D6_n$

TRUTH TABLE (Continued)

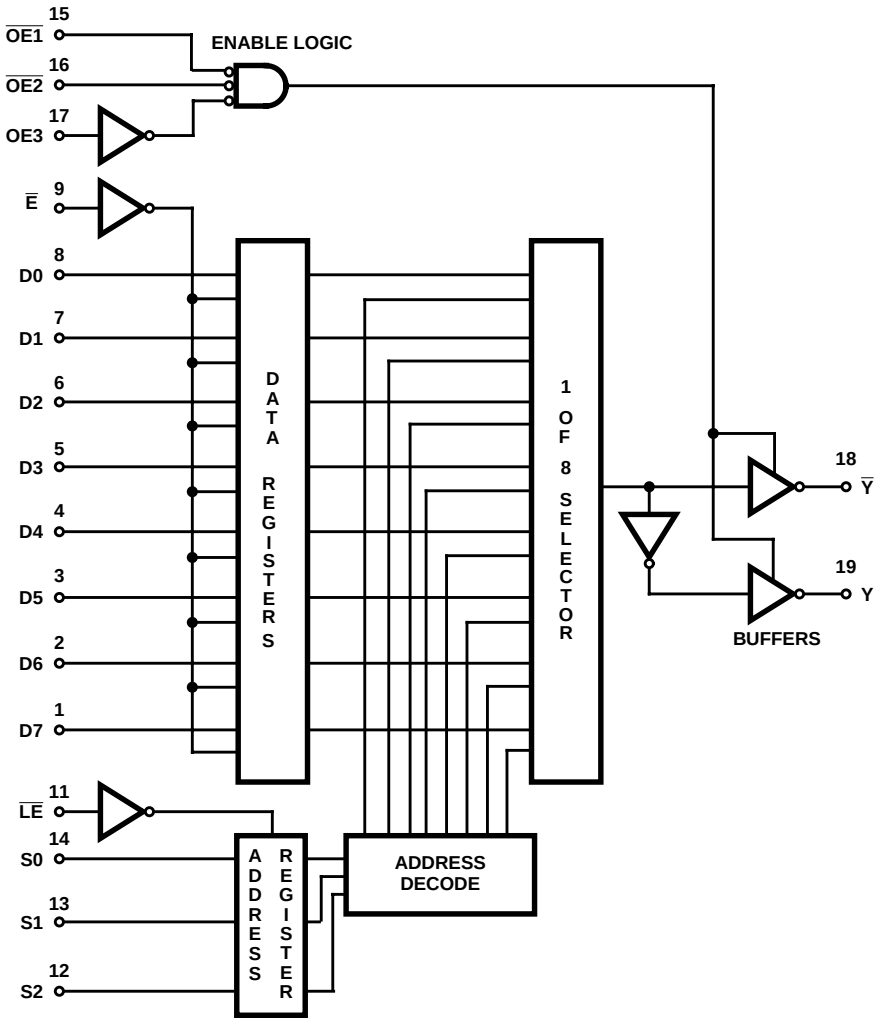
INPUTS							OUTPUTS	
SELECT (NOTE 1)			ENABLE DATA	OUTPUT ENABLES				
S2	S1	S0	$\overline{E}$	$\overline{OE1}$	$\overline{OE2}$	OE3	$\overline{Y}$	Y
H	H	H	L	L	L	H	$\overline{D7}$	D7
H	H	H	H	L	L	H	$\overline{D7}_n$	$D7_n$

H = High Voltage Level (Steady State); L = Low Voltage Level (Steady State); X = Don't Care; Z = High Impedance State (Off State); $D0_n...D7_n$ = the level of steady-state inputs D0 through D7, respectively, before the most recent low-to-high transition of data control.

NOTE:

1. This column shows the input address setup with $\overline{LE}$ low.

Block Diagram



Logic Diagram

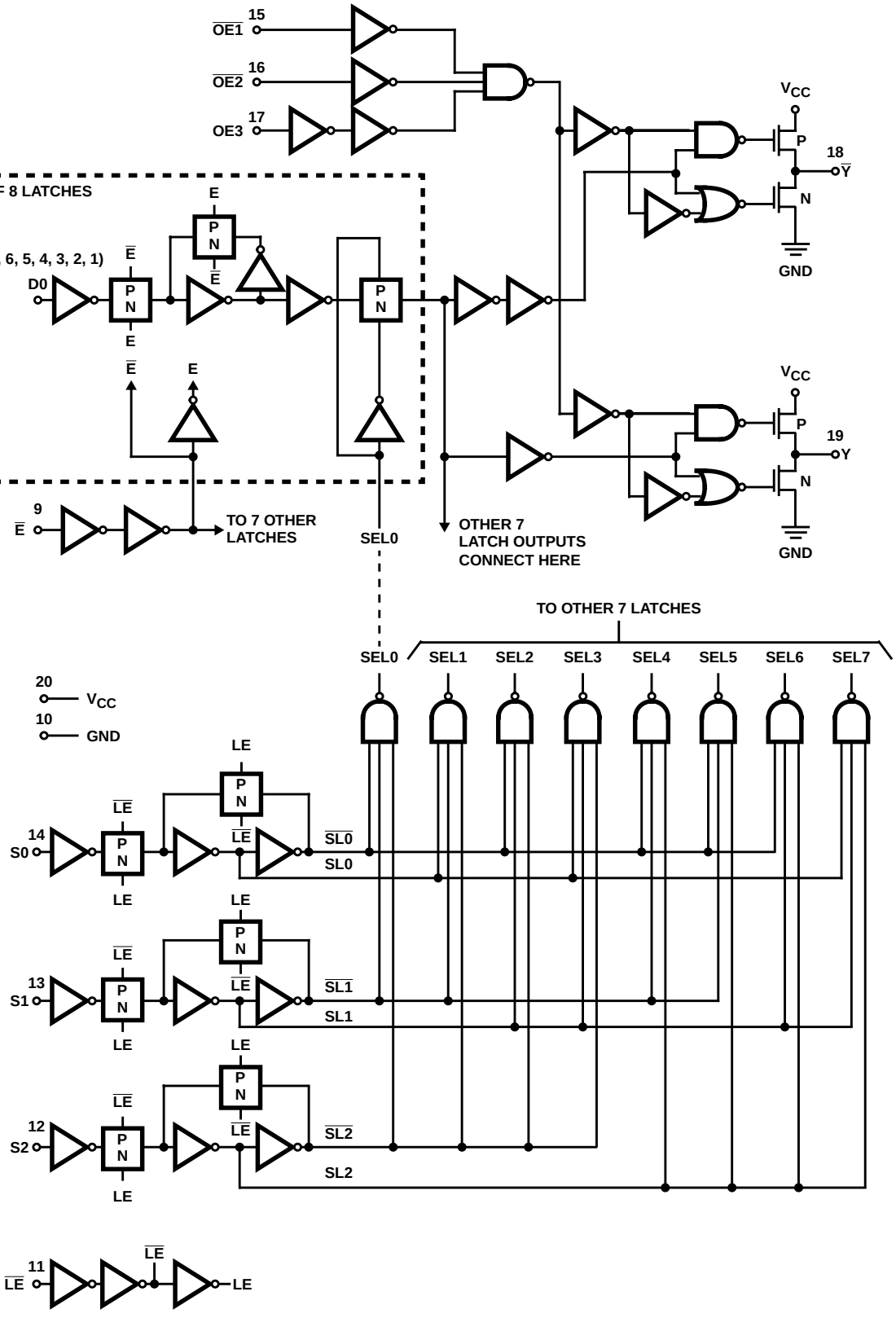


FIGURE 1. HC/HCT354 LOGIC DIAGRAM

Absolute Maximum Ratings

DC Supply Voltage, V_{CC} . . . . . -0.5V to 7V
DC Input Diode Current, I_{IK}
For V_I < -0.5V or V_I > V_{CC} + 0.5V . . . . . ±20mA
DC Output Diode Current, I_{OK}
For V_O < -0.5V or V_O > V_{CC} + 0.5V . . . . . ±20mA
DC Drain Current, per Output, I_O
For -0.5V < V_O < V_{CC} + 0.5V . . . . . ±35mA
DC Output Source or Sink Current per Output Pin, I_O
For V_O > -0.5V or V_O < V_{CC} + 0.5V . . . . . ±25mA
DC V_{CC} or Ground Current, I_{CC} . . . . . ±50mA

Operating Conditions

Temperature Range, T_A . . . . . -55°C to 125°C
Supply Voltage Range, V_{CC}
HC Types . . . . . 2V to 6V
HCT Types . . . . . 4.5V to 5.5V
DC Input or Output Voltage, V_I, V_O . . . . . 0V to V_{CC}
Input Rise and Fall Time
2V . . . . . 1000ns (Max)
4.5V. . . . . 500ns (Max)
6V . . . . . 400ns (Max)

Thermal Information

Thermal Resistance (Typical, Note 2) θ_{JA} (°C/W)
E (PDIP) Package 69
Maximum Junction Temperature . . . . . 150°C
Maximum Storage Temperature Range . . . . . -65°C to 150°C
Maximum Lead Temperature (Soldering 10s) . . . . . 300°C
(SOIC - Lead Tips Only)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

2. The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		V_{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V_I (V)	I_O (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES												
High Level Input Voltage	V_{IH}	-	-	2	1.5	-	-	1.5	-	1.5	-	V
				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input Voltage	V_{IL}	-	-	2	-	-	0.5	-	0.5	-	0.5	V
				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output Voltage CMOS Loads	V_{OH}	V_{IH} or V_{IL}	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output Voltage TTL Loads (Bus Driver)			-6	4.5	3.98	-	-	3.84	-	3.7	-	V
			-7.8	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	V_{OL}	V_{IH} or V_{IL}	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads (Bus Driver)			6	4.5	-	-	0.26	-	0.33	-	0.4	V
			7.8	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I_I	V_{CC} or GND	-	6	-	-	±0.1	-	±1	-	±1	µA

DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS		V_{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V_I (V)	I_O (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Quiescent Device Current	I_{CC}	V_{CC} or GND	0	6	-	-	8	-	80	-	160	µA
Three-State Leakage Current	I_{OZ}	V_{IL} or V_{IH}	V_O = V_{CC} or GND	6	-	-	±0.5	-	±5.0	-	±10	µA
HCT TYPES												
High Level Input Voltage	V_{IH}	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V_{IL}	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V_{OH}	V_{IH} or V_{IL}	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V_{OL}	V_{IH} or V_{IL}	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I_I	V_{CC} to GND	-	5.5	-	-	±0.1	-	±1	-	±1	µA
Quiescent Device Current	I_{CC}	V_{CC} or GND	0	5.5	-	-	8	-	80	-	160	µA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI_{CC} (Note 3)	V_{CC} -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	µA
Three-State Leakage Current	I_{OZ}	V_{IL} or V_{IH}	V_O = V_{CC} or GND	5.5	-	-	±0.5	-	±5.0	-	±10	µA

NOTE:

3. For dual-supply systems theoretical worst case (V_I = 2.4V, V_{CC} = 5.5V) specification is 1.8mA.

HCT Input Loading Table

INPUT	UNIT LOADS
D0-D7	0.50
S0, S1, S3	0.70
$\overline{OE1}$, $\overline{OE2}$	0.80
OE3	0.25
$\overline{LE}$	0.25
$\overline{E}$	0.60

NOTE: Unit Load is ΔI_{CC} limit specified in DC Electrical Specifications table, e.g., 360µA max at 25°C.

Prerequisite For Switching Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	V_{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES											
$\overline{E}$ Pulse Width	t_{PLH}, t_{PHL}	-	2	80	-	-	100	-	120	-	ns
			4.5	16	-	-	20	-	24	-	ns
			6	14	-	-	17	-	20	-	ns
$\overline{LE}$ Pulse Width	t_{PLH}, t_{PHL}	-	2	80	-	-	100	-	120	-	ns
			4.5	16	-	-	20	-	24	-	ns
			6	14	-	-	17	-	20	-	ns
Set-up Times Dn → $\overline{E}$	t_{SU}	-	2	50	-	-	65	-	75	-	ns
			4.5	10	-	-	13	-	15	-	ns
			6	9	-	-	11	-	13	-	ns
Set-up Times Sn → $\overline{LE}$	t_{SU}	-	2	50	-	-	65	-	75	-	ns
			4.5	10	-	-	13	-	15	-	ns
			6	9	-	-	11	-	13	-	ns
Hold Times Dn → $\overline{E}$	t_H	-	2	45	-	-	55	-	70	-	ns
			4.5	9	-	-	11	-	14	-	ns
			6	8	-	-	9	-	12	-	ns
Hold Times Sn → $\overline{LE}$	t_H	-	2	45	-	-	55	-	70	-	ns
			4.5	9	-	-	11	-	14	-	ns
			6	8	-	-	9	-	12	-	ns
HCT TYPES											
$\overline{E}$ Pulse Width	t_{PLH}, t_{PHL}	-	4.5	16	-	-	20	-	24	-	ns
$\overline{LE}$ Pulse Width	t_{PLH}, t_{PHL}	-	4.5	16	-	-	20	-	24	-	ns
Set-up Times Dn → $\overline{E}$	t_{SU}	-	4.5	10	-	-	13	-	15	-	ns
Set-up Times Sn → $\overline{LE}$	t_{SU}	-	4.5	10	-	-	13	-	15	-	ns
Hold Times Dn → $\overline{E}$	t_H	-	4.5	9	-	-	11	-	14	-	ns
Hold Times Sn → $\overline{LE}$	t_H	-	4.5	9	-	-	11	-	14	-	ns

Switching Specifications Input t_r, t_f = 6ns

PARAMETER	SYMBOL	TEST CONDITIONS	V_{CC} (V)	25°C		-40°C TO 85°C	-55°C TO 125°C	UNITS
				TYP	MAX	MAX	MAX	
HC TYPES								
Propagation Delay, Dn → Y, $\overline{Y}$	t_{PLH}, t_{PHL}	C_L = 50pF	2	-	210	265	315	ns
			4.5	-	42	53	63	ns
			6	-	36	45	54	ns
		C_L = 15pF	5	18	-	-	-	ns
Propagation Delay, $\overline{E}$ → Y, $\overline{Y}$	t_{PLH}, t_{PHL}	C_L = 50pF	2	-	250	315	375	ns
			4.5	-	50	63	75	ns
			6	-	43	54	64	ns
		C_L = 15pF	5	21	-	-	-	ns

Switching Specifications Input t_r, t_f = 6ns **(Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS	V_{CC} (V)	25°C		-40°C TO 85°C	-55°C TO 125°C	UNITS
				TYP	MAX	MAX	MAX	
Propagation Delay, Sn → Y, $\overline{Y}$	t_{PLH}, t_{PHL}	C_L = 50pF	2	-	260	325	390	ns
			4.5	-	52	65	78	ns
			6	-	44	55	66	ns
		C_L = 15pF	5	22	-	-	-	ns
Propagation Delay, $\overline{LE}$ → Y, $\overline{Y}$	t_{PLH}, t_{PHL}	C_L = 50pF	2	-	290	365	435	ns
			4.5	-	58	73	87	ns
			6	-	49	62	74	ns
		C_L = 15pF	5	24	-	-	-	ns
Output Disabling Time, $\overline{OE}$n to Y, $\overline{Y}$	t_{PLZ}, t_{PHZ}	C_L = 50pF	2	-	155	195	235	ns
			4.5	-	31	39	47	ns
			6	-	26	33	40	ns
		C_L = 15pF	5	13	-	-	-	ns
Output Disabling Time, OE3 to Y, $\overline{Y}$	t_{PLZ}, t_{PHZ}	C_L = 50pF	2	-	155	195	235	ns
			4.5	-	31	39	47	ns
			6	-	26	33	40	ns
		C_L = 15pF	5	13	-	-	-	ns
Output Enabling Time, $\overline{OE}$n to Y, $\overline{Y}$	t_{PZL}, t_{PZH}	C_L = 50pF	2	-	150	190	225	ns
			4.5	-	30	38	45	ns
			6	-	26	33	38	ns
		C_L = 15pF	5	12, 13	-	-	-	ns
Output Enabling Time, OE3 to Y, $\overline{Y}$	t_{PZL}, t_{PZH}	C_L = 50pF	2	-	160	200	240	ns
			4.5	-	32	40	48	ns
			6	-	27	34	41	ns
		C_L = 15pF	5	12, 13	-	-	-	ns
Output Transition Time	t_{TLH}, t_{THL}	C_L = 50pF	2	-	60	75	90	ns
			4.5	-	12	15	18	ns
			6	-	10	13	15	ns
Input Capacitance	C_I	-	-	-	10	10	10	pF
Three-State Capacitance	C_O	-	-	-	20	20	20	pF
Power Dissipation Capacitance (Notes 4, 5)	C_{PD}	-	5	90	-	-	-	pF
HCT TYPES								
Propagation Delay, Dn → Y, $\overline{Y}$	t_{PLH}, t_{PHL}	C_L = 50pF	4.5	-	47	59	71	ns
		C_L = 15pF	5	20	-	-	-	ns
Propagation Delay, $\overline{E}$ → Y, $\overline{Y}$	t_{PLH}, t_{PHL}	C_L = 50pF	4.5	-	54	68	81	ns
		C_L = 15pF	5	23	-	-	-	ns

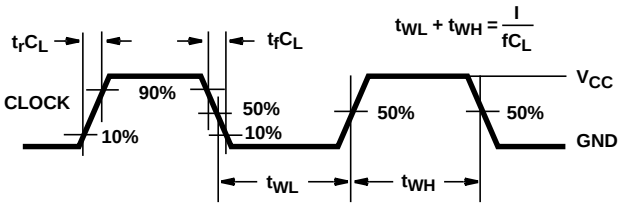
Switching Specifications Input t_r, t_f = 6ns **(Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS	V_{CC} (V)	25°C		-40°C TO 85°C	-55°C TO 125°C	UNITS
				TYP	MAX	MAX	MAX	
Propagation Delay, Sn → Y, $\overline{Y}$	t_{PLH}, t_{PHL}	C_L = 50pF	4.5	-	59	74	89	ns
		C_L = 15pF	5	25	-	-	-	ns
Propagation Delay, $\overline{LE}$ → Y, $\overline{Y}$	t_{PLH}, t_{PHL}	C_L = 50pF	4.5	-	63	79	94	ns
		C_L = 15pF	5	25	-	-	-	ns
Output Disabling Time, $\overline{OE}$n to Y, $\overline{Y}$	t_{PLZ}, t_{PHZ}	C_L = 50pF	4.5	-	33	41	50	ns
		C_L = 15pF	5	13, 16	-	-	-	ns
Output Disabling Time, OE3 to Y, $\overline{Y}$	t_{PLZ}, t_{PHZ}	C_L = 50pF	4.5	-	39	49	59	ns
		C_L = 15pF	5	13, 16	-	-	-	ns
Output Enabling Time, $\overline{OE}$n to Y, $\overline{Y}$	t_{PZL}, t_{PZH}	C_L = 50pF	4.5	-	34	43	51	ns
		C_L = 15pF	5	14	-	-	-	ns
Output Enabling Time, OE3 to Y, $\overline{Y}$	t_{PZL}, t_{PZH}	C_L = 50pF	4.5	-	34	43	51	ns
		C_L = 15pF	5	14	-	-	-	ns
Output Transition Time	t_{TLH}, t_{THL}	C_L = 50pF	4.5	-	12	15	18	ns
Input Capacitance	C_{IN}	-	-	-	10	10	10	pF
Three-State Capacitance	C_O	-	-	-	20	20	20	pF
Power Dissipation Capacitance (Notes 4, 5)	C_{PD}	-	5	92	-	-	-	pF

NOTES:

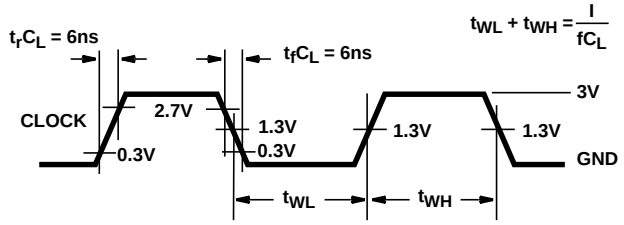
4. C_{PD} is used to determine the dynamic power consumption, per device.
5. $P_D = V_{CC}^2 (C_{PD} + C_L)$ where f_i = Input Frequency, C_L = Output Load Capacitance, V_{CC} = Supply Voltage.

Test Circuits and Waveforms



NOTE: Outputs should be switching from 10% V_{CC} to 90% V_{CC} in accordance with device truth table. For f_{MAX}, input duty cycle = 50%.

FIGURE 2. HC CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH



NOTE: Outputs should be switching from 10% V_{CC} to 90% V_{CC} in accordance with device truth table. For f_{MAX}, input duty cycle = 50%.

FIGURE 3. HCT CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH

Test Circuits and Waveforms (Continued)

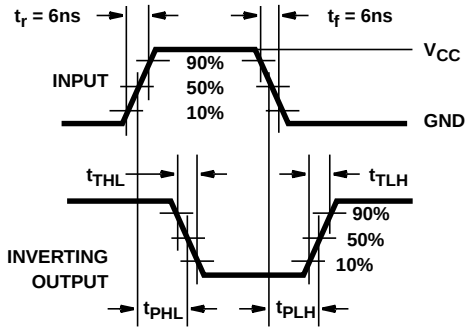


FIGURE 4. HC AND HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

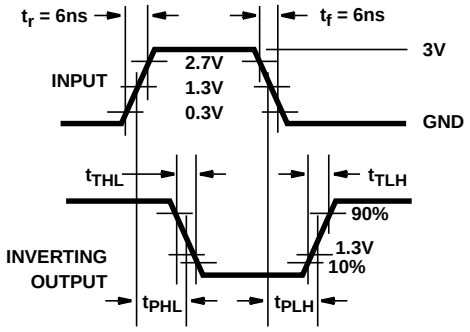


FIGURE 5. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

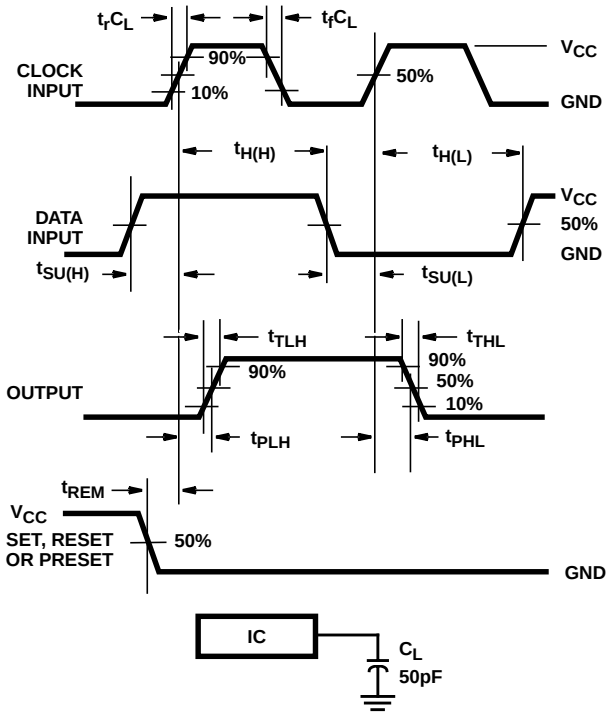


FIGURE 6. HC SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

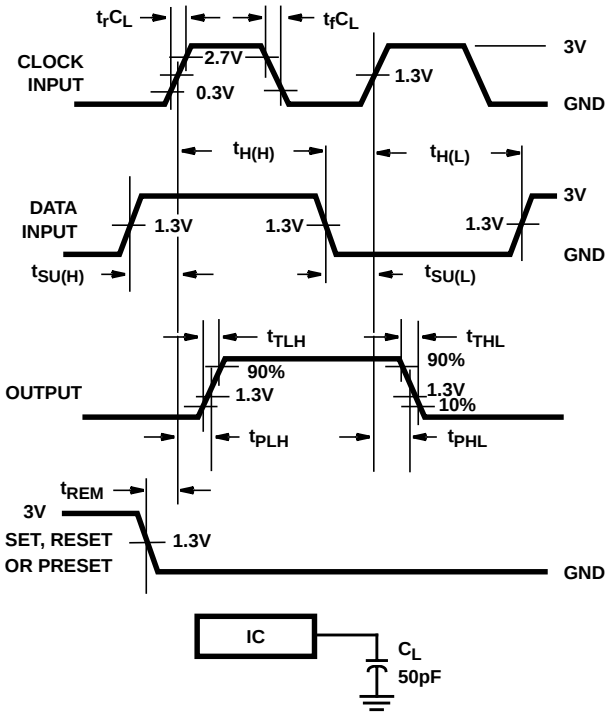


FIGURE 7. HCT SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

Test Circuits and Waveforms (Continued)

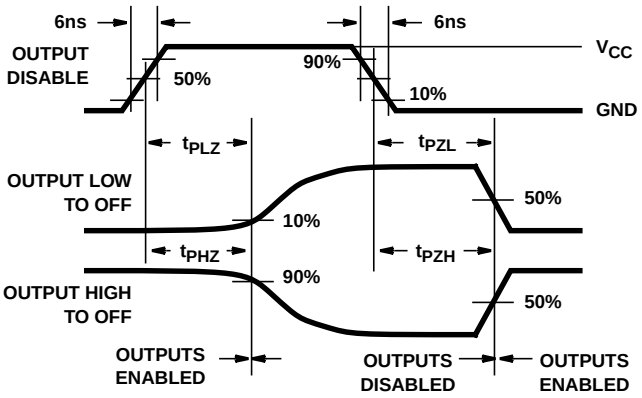


FIGURE 8. HC THREE-STATE PROPAGATION DELAY WAVEFORM

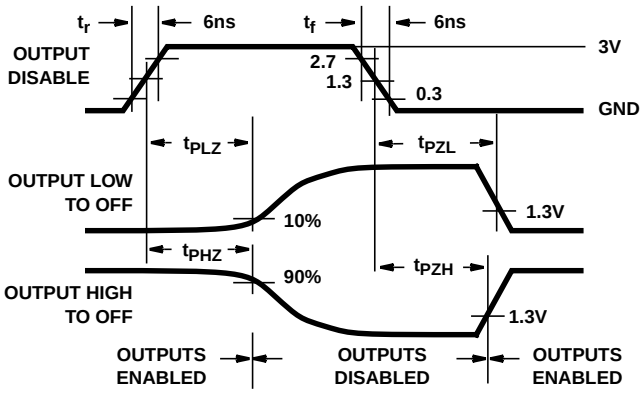
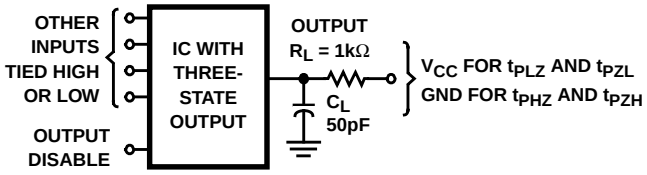


FIGURE 9. HCT THREE-STATE PROPAGATION DELAY WAVEFORM



NOTE: Open drain waveforms t_{PLZ} and t_{PZL} are the same as those for three-state shown on the left. The test circuit is Output R_L = 1kΩ to V_{CC}, C_L = 50pF.

FIGURE 10. HC AND HCT THREE-STATE PROPAGATION DELAY TEST CIRCUIT

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
CD54HC354F3A	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
CD74HC354E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HC354EE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HCT354E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HCT354EE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

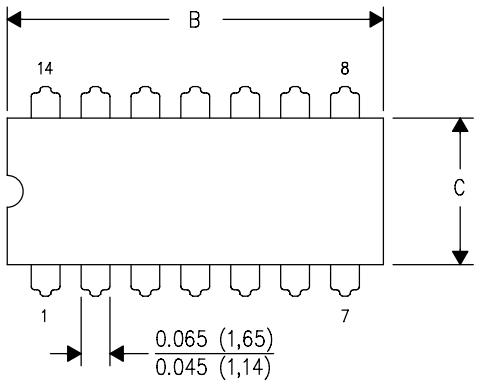
(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

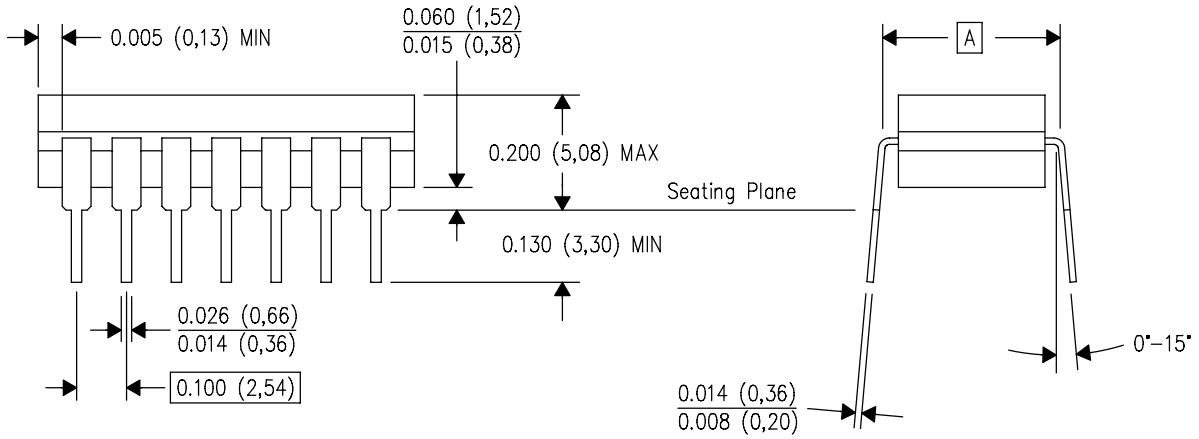
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



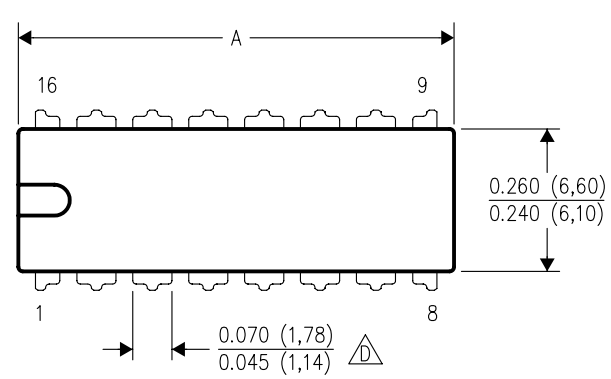
4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

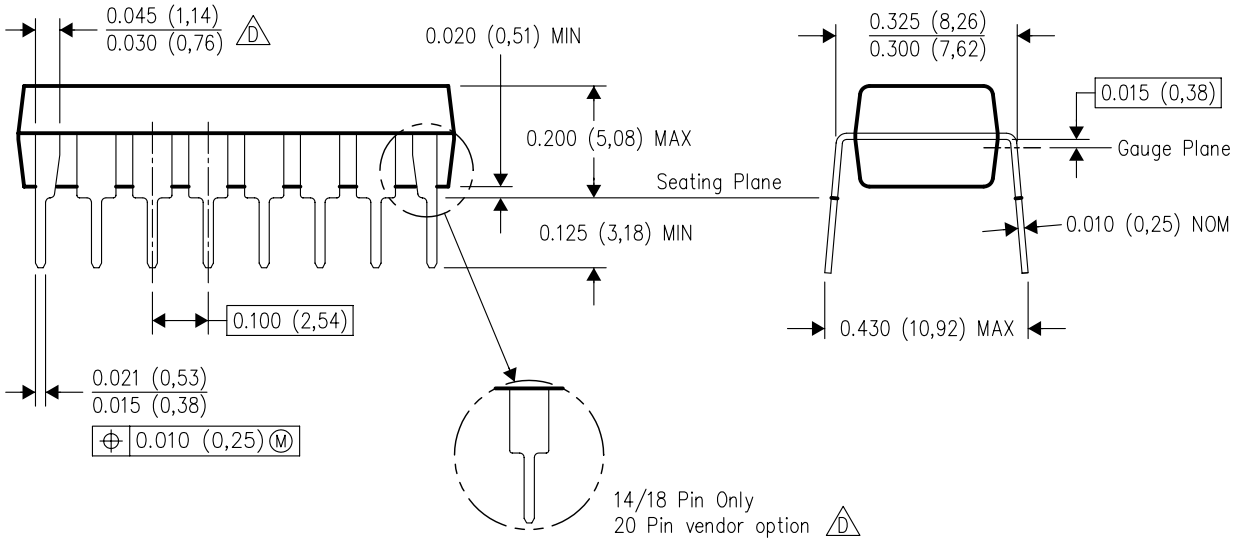
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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